

# SEMICONDUCTOR DEVICE AND ITS MANUFACTURE

Patent number: JP11135712  
 Publication date: 1999-05-21  
 Inventor: SHINTANI TADAYUKI  
 Applicant: KYUSHU NIPPON ELECTRIC  
 Classification:  
 - international: H01L25/00; H01L25/04; H01L25/18  
 - european:  
 Application number: JP19970294363 19971027  
 Priority number(s): JP19970294363 19971027

BEST AVAILABLE

BEST AVAILABLE

Report a data error here

## Abstract of JP11135712

**PROBLEM TO BE SOLVED:** To provide a package requiring no lead machining, since it has become increasingly difficult to perform the lead machining due to the tendency toward increase in the number of pins. **SOLUTION:** Although signal transmission with the external device of a semiconductor device 2 built into a package 11 is normally made via an external lead, a device has package structure where a function block 8 that has transmission and reception parts in the same package, transmits and receives a signal by radio, and at the same time rectifies the signal as a current source is mounted, thus omitting the external lead of the package 11 and obtaining a semiconductor device without requiring the need for complex lead machining.

